

DDR4 SERIES

Amphenol
Commercial Products

DDR4-288-S-XX-X-X-X



DDR4-288-V-XX-X-X-T-X



Features:

- Smaller pitch and lower operating voltage
- Supports faster data rates
- Reduced product width
- Various pin tail lengths for PCB thickness

Overview:

- Complies to new interface standard JEDEC POD12
- Nylon 9T halogen free housing for reflow process
- Matte tin plating on contact soldering area for lead-free soldering process
- Supports module variants in UDIMM, RDIMM and LRDIMM
- Allows module seating plane of 2.4mm Max
- Accepts module thickness of 1.4mm

Applications:

- Storage
- Servers
- Desktops
- Industrial Computers

Ordering Information:

Termination		DDR4	288	X	XX	X	X	X	X	Latch Option	
V	TH type									Blank	Small
S	SMT type									F	Big
Dip Options (Dim A, Dim B, Dim C)										Packing Code	
* TH Type	01	2.10mm, 3.94mm, 1.57mm								T	Soft tray
	02	2.67mm, 3.94mm, 1.57mm								H	Hard tray (only SMT type)
	03	3.95mm, 4.60mm, 2.36mm									
	04	3.18mm, 4.60mm, 2.36mm									
** SMT Type	01	3.94mm, 1.57mm ***									
	02	3.94mm, 1.57mm									
	03	4.60mm, 2.36mm ***									
	04	4.60mm, 2.36mm									
	05	2.00mm, 1.57mm ***									
	06	2.00mm, 1.57mm									
										Contact Area Plating	
										0	Gold flash
										1	15µ" gold
										2	20µ" gold
										3	30µ" gold
										4	3µ" gold over 12µ" PdNi
										5	3µ" gold over 27µ" PdNi
										Color of Housing/Latch	
										1	Black/Black
										2	Black/Natural
										3	Natural/Black
										4	Natural/Natural
										5	Blue/Natural
										6	Green/Natural
										7	Blue/Blue



* TH Type Note:
Dim A = Pin tail length
Dim B = Board lock length
Dim C = Recommended PCB thickness

** SMT Type Note:
Dim A = Board lock length
Dim B = Recommended PCB thickness

*** With Mylar for Pick and Place assembly equipment



To learn more about DDR4 connectors:

web: amphenolcanada.com

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Mechanical	
Insertion Force	10.88Kgf max.
Withdrawal Force	14gf min. (per contact pair)
Retention Force	Contact: 0.30Kgf min. Boardlock: 1.36Kgf min.
Durability	Contact resistance: ΔR : 10m Ω max. after test
Vibration, Mechanical Shock	No physical damage Discontinuity < 1 μ s Contact resistance: ΔR : 10m Ω max. after test
Reseating	No damage
Latch Overstress Force	3.5kg min. force held for 10s with no damage
Latch Actuation Force	The force to fully actuate the latch open shall be 4.5kgf max. per latch
Module Rip Out Force	9.1kgf min. retention force of the module in connector with no damage
Retention of Connector to PCB	No lifting of connector from applicable PCB
Insertion Force of Connector into PCB	Total insertion force to be 6.8kgf max.

Materials	
Insulator	High temp. thermal plastic, UL94V-0, Color-option
Contacts	Copper alloy
	a) Gold flash or b) 15 microinches minimum of gold or c) 30 microinches minimum or gold
	Contact Area
	Solder Area
Boardlock	Tin or matte tin plating
	Underplate
	Nickel plating over all
	Copper alloy
Boardlock	Tin plating
	Solder Area
	Underplate
	Nickel plating overall

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